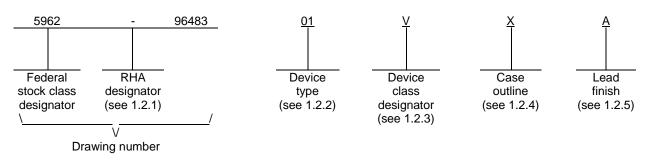
								•		ONS										
LTR					[DESCR	IPTION	N					DA	TE (YF	R-MO-	DA)		APPF	ROVED	
A	Under Table IIA, delete footnote <u>2</u> / from final electrical parameters of device class V. Under the footnote <u>2</u> / description of Table IIA, delete the word "interim" and substitute the word "endpoint". Changes in accordance with N.O.R. 5962-R040-97.					ce	96-11-04			R. M	NINNC									
В	Make Chan	chang ges in	es to th accorda	ne sym ance w	bol "L" rith N.C	dimens D.R. 596	sions ui 62-R01	nder ca 8-99.	ase outl	line X.				99-0)1-15			R. M	ONNIN	
С	Add c	case ou	tline Z.	. Make	editor	ial char	nges th	rougho	ut. Re	drawn.	- ro			00-0)4-14			R. M	ONNIN	
D	Repla	ace refe	rence	to MIL-	-STD-9	73 with	refere	nce to	MIL-PF	RF-3853	35 r	0		08-0	06-03			R. H	EBER	
Е						s M req curren			535 rec	quireme	ents	ro		16-0	08-03			C. S/	AFFLE	
REV	1 1																			
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SHEET REV SHEET REV STATUS				REV			E	E	E	E	E	E	E	E	E	E				
SHEET REV SHEET REV STATUS OF SHEETS				SHE	ET		E 1	E 2	E 3	E 4	E 5	E 6	E 7	E 8	E 9	E 10				
SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A				SHE PREI RA.	ET PARED JESH F	PITHAD	1					6 CC	7 DLA I DLUM	8 LAND IBUS,	9 AND , OHIO	10 0 MAR 0 432	218-3	990		
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SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A MICR(DR THIS DRAWI FOR L DEPA AND AGE DEPARTME	NDAR OCIRC AWING ING IS AV USE BY A ARTMEN ENCIES C	CUIT G VAILAE ALL TS DF THE DEFENS		SHE PREI RA. CHE RA. APPF MIC	ET PAREL JESH F CKED JESH F ROVEL CHAEL WING	PITHAD BY PITHAD D BY A. FRY APPRC	1 11A 11A 17E 10VAL D 4-10	2		4 MIC DIC	5 ROC	6 CC http: CIRCU 1.2 V	7 DLA I DLUM //www	8 BUS, w.land LINE/ S, MC	9 O AND , OHIO dandi	10 O MAR O 432 mariti	218-3 me.d AGE C SII	990 Ila.mil	EREN	

1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device class Q) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.

1.2 <u>PIN</u>. The PIN is as shown in the following example:



1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	<u>Generic number</u>	Circuit function
01 02	LM113 LM113-1	Voltage reference diode Voltage reference diode
03	LM113-2	Voltage reference diode

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation						
Q or V	Certification and qualification to MIL-PRF-38535						
1.2.4 Case outline(s).	The case outline(s) are as design	ated in MIL-STD-1835	and as follows:				
Outline letter	Descriptive designator	<u>Terminals</u>	Package style				
Х	See figure 1	2	TO-46 can				
Z	GDFP1-G10	10	Flat pack with gull wing leads				

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V.

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1.3 Absolute maximum ratings. 1/ Reverse current 50 mA Forward current 50 mA Maximum power dissipation (PD): 50 mA Cases X and Z 100 mW 2/ Storage temperature range (TSTG) -65°C to +150°C Lead temperature (soldering, 10 seconds) +300°C

 Junction temperature (TJ)
 +150°C

 Thermal resistance, junction-to-case (θJC):
 80°C/W

 Case X
 80°C/W

 Case Z
 27°C/W

 Thermal resistance, junction-to-ambient (θJA):
 440°C/W

 Case Z
 218°C/W

1.4 Recommended operating conditions.

Ambient operating temperature (TA)--55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings. MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <u>http://quicksearch.dla.mil</u> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ Rating applies at 25°C ambient without heat sink. For operating at elevated temperature the device must be derated based on a 150°C maximum junction and a thermal resistance of 80°C/W for case X and 27°C/W for case Z junction to case or 440°C/W for case X and 218°C/W for case Z junction to ambient.

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3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 as specified herein, or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V.

3.2.1 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.4 herein.

3.2.2 <u>Case outline dimensions and terminal connections</u>. The case outline dimensions and terminal connections shall be as specified on figure 1.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535.

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein. The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 shall be provided with each lot of microcircuits delivered to this drawing.

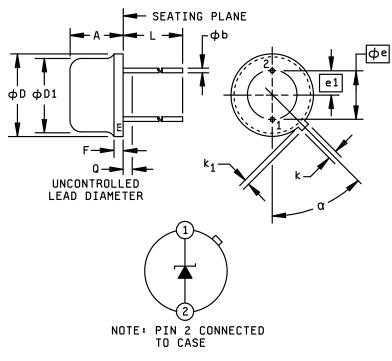
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	т	ABLE I. Electrical performance	e characteristic	<u>s</u> .			
Test	Symbol	$\begin{array}{l} \mbox{Conditions} \underline{1}/\\ -55^{\circ}\mbox{C} \leq T_A \leq +125^{\circ}\mbox{C}\\ \mbox{unless otherwise specified} \end{array}$	Group A subgroups	Device type	Lir	nits	Unit
					Min	Max	
Zener voltage	Vzr	IR = 1 mA	1	01	1.16	1.28	V
			2,3		1.157	1.283	
			1	02	1.210	1.232	-
			2,3		1.206	1.234	
			1	03	1.195	1.245	
			2,3		1.194	1.246	
Delta zener voltage	ΔVZR	$0.5 \text{ mA} \le IR \le 20 \text{ mA}$	1	All		15	mV
		$0.5 \text{ mA} \le I_R \le 10 \text{ mA}$	2,3			15	
Forward voltage drop	VF	IF = 1 mA	1,2,3	All		1	V
Reverse dynamic impedance	RR	IR = 1 mA <u>2</u> /	4	All		1	Ω
		IR = 10 mA <u>2</u> /	1			0.8	

<u>1</u>/ At high currents, breakdown voltage should be measured with lead lengths less than 0.25 inch. Kelvin contact sockets are also recommended. The diode should not be operated with shunt capacitance between 200 pF and 0.1 μ F, unless isolated by at least a 100 Ω resistor, as it may oscillate at some currents.

 $\underline{2}$ / If not tested, shall be guaranteed to the limits specified in table I herein.

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TOP VIEW

Symbol			Notes		
	Inc	hes	Millim	neters	
	Min	Max	Min	Max	
А	.080	.105	2.03	2.67	
φb	.016	.019	0.41	0.48	
φD	.209	.219	5.31	5.56	
φD1	.178	.195	4.52	4.95	
е	.100	BSC	2.54		
e1	.050	BSC	1.27		
F		.030		0.76	
k	.036	.046	0.91	1.17	
k1	.028	.048	0.28	1.22	
L	.500		12.70		
Q		.025		0.64	
α	45°	BSC	45°	BSC	2

NOTES:

- 1. The U.S. government preferred system of measurement is the metric SI system. However, this item was originally designated using inch-pound units of measurement. In the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. α is the basis spacing from the centerline of the tab to terminal 1.

FIGURE 1. Case outline dimensions and terminal connections.

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Device type	01
Case outline	Z
Terminal number	Terminal number
1	NC
2	NC
3	NC
4	NC
5	-V
6	NC
7	NC
8	NC
9	NC
10	+V

FIGURE 1. <u>Case outline dimensions and terminal connections</u> – Continued.

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4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

- 4.2.1 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections, and as specified herein.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

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Test requirements	Subgroups	
·	(in accordance with	
	MIL-PRF-38535, table III)	
	Device	Device
	class Q	class V
Interim electrical		
parameters (see 4.2)		
Final electrical	1, 2, 3, 4 <u>1</u> /	1, 2, 3, 4 <u>1</u> /
parameters (see 4.2)		
Group A test	1, 2, 3, 4	1, 2, 3, 4
requirements (see 4.4)		
Group C end-point electrical	1, 2, 3	1, 2, 3 <u>2</u> /
parameters (see 4.4)		
Group D end-point electrical	1, 2, 3	1, 2, 3
parameters (see 4.4)		
Group E end-point electrical		
parameters (see 4.4)		

TABLE IIA. Electrical test requirements.

<u>1</u>/ PDA applies to subgroup 1.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be completed with reference to the previous electrical parameters.

TABLE IIB.	Delta limits at +25°C.
------------	------------------------

Parameter <u>1</u> /	Device type	Limit
Vzr	All	±0.02 V

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at TA = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V.

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6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-8108.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 16-08-03

Approved sources of supply for SMD 5962-96843 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at https://landandmaritimeapps.dla.mil/Programs/Smcr/.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-9684301VXA	<u>3</u> /	LM113H-QMLV
5962-9684301VZA	01295	LM113WG-QMLV
5962-9684302VXA	01295	LM113-1H-QMLV
5962-9684302VZA	01295	LM113-1WG-QMLV
5962-9684303VXA	<u>3</u> /	LM113-2H-QMLV

- <u>1</u>/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- $\underline{3}$ / Not available from an approved source of supply.

Vendor CAGE number

01295

Vendor name and address

Texas Instruments, Inc. Semiconductor Group 8505 Forest Lane P.O. Box 660199 Dallas, TX 75243

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.